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ITLE: Process for cleaning showerhead for a chemical vapor deposition chamber

IVENTOR: JU, T; RUAN, J; SHR, H; YANG, N

ATENT-ASSIGNEE:

SSIGNEE

CODE

INBOND ELECTRONICS CORP

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BSTRACTED-PUB-NO: TW 460611A

ASIC-ABSTRACT:

OVELTY - The present invention provides a process for cleaning a showerhead for a chemical vapor leposition chamber. First, the showerhead is dipped into an alkaline reagent containing ammonium water so as to remove aluminum fluoride attached on the showerhead. Subsequently, the residual thraining component, and the aluminum fluoride is obtained from the reaction of a plasma of a fluorine-containing gas used for cleaning the chamber and aluminum. By using the ammonia water-containing alkaline reagent, the showerhead for a chemical vapor deposition chamber can be effectively cleaned. Thus, the process stability can be increased and the life span of the showerhead can be lengthened.

CHOSEN-DRAWING: Dwg.0/1

CITLE-TERMS: PROCESS CLEAN CHEMICAL VAPOUR DEPOSIT CHAMBER

DERWENT-CLASS: M12

CPI-CODES: M12-A05;